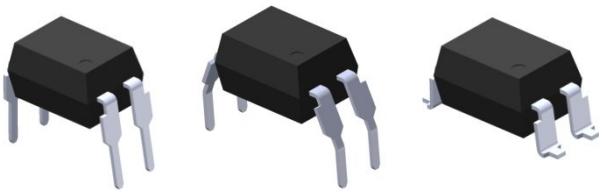




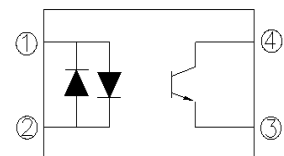
# THE DATASHEET OF EL814M



### 4 PIN DIP PHOTOTRANSISTOR PHOTOCOUPLER AC INPUT PHOTOCOUPLER EL814 Series



Schematic



Pin Configuration

1. Anode / Cathode
2. Cathode / Anode
3. Emitter
4. Collector

#### Features:

- AC input response
- Current transfer ratio (CTR: Min. 20% at  $I_F = \pm 1\text{mA}$ ,  $V_{CE} = 5\text{V}$ )
- High isolation voltage between input and output (Viso=5000 V rms )
- Wide Operating temperature range  $-55\sim 110^\circ\text{C}$
- High collector-emitter voltage  $V_{CEO}=80\text{V}$
- Compact dual-in-line package
- Pb free and RoHS compliant.
- UL approved (No. E214129)
- VDE approved (No. 132249)
- SEMKO approved
- NEMKO approved
- DEMKO approved
- FIMKO approved
- CSA approved
- CQC approved

#### Description

The EL814 series of devices each consist of two infrared emitting diodes, connected in inverse parallel, optically coupled to a phototransistor detector. They are packaged in a 4-pin DIP package and available in side-lead spacing and SMD option.

#### Applications

- AC line monitor
- Programmable controllers
- Telephone line interface
- Unknown polarity DC sensor

**Absolute Maximum Ratings (Ta=25 °C)**

	Parameter	Symbol	Rating	Unit
Input	Forward current	$I_F$	±60	mA
	Peak forward current (t = 10µs)	$I_{FM}$	1	A
	Power dissipation	$P_D$	100	mW
	Derating factor (above 100 °C)		2.9	mW/°C
Output	Power dissipation	$P_C$	150	mW
	Derating factor (above 100 °C)		5.8	mW/°C
	Collector-Emitter voltage	$V_{CEO}$	80	V
	Emitter-Collector voltage	$V_{ECO}$	6	V
Total Power Dissipation		$P_{TOT}$	200	mW
Isolation Voltage*1		$V_{ISO}$	5000	V rms
Operating Temperature		$T_{OPR}$	-55 to 110	°C
Storage Temperature		$T_{STG}$	-55 to 125	°C
Soldering Temperature*2		$T_{SOL}$	260	°C

Notes:

\*1 AC for 1 minute, R.H.= 40 ~ 60% R.H. In this test, pins 1, 2 are shorted together, and pins 3, 4 are shorted together.

\*2 For 10 seconds

**Electro-Optical Characteristics (Ta=25 unless specified otherwise)**

**Input**

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Forward Voltage	$V_F$	-	1.2	1.4	V	$I_F = \pm 20\text{mA}$
Input capacitance	$C_{in}$	-	50	250	pF	$V = 0, f = 1\text{KHz}$

**Output**

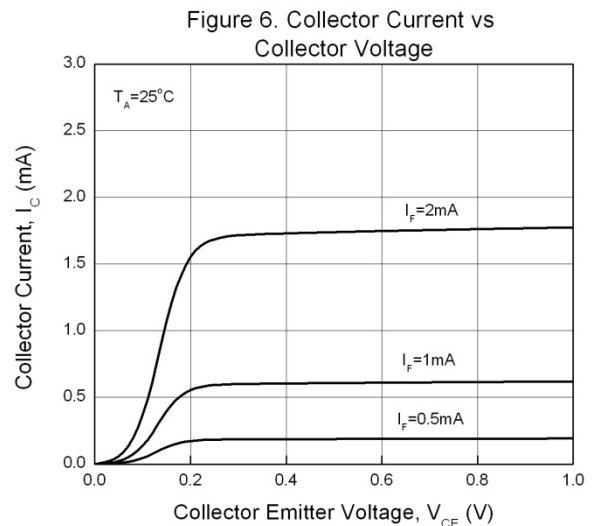
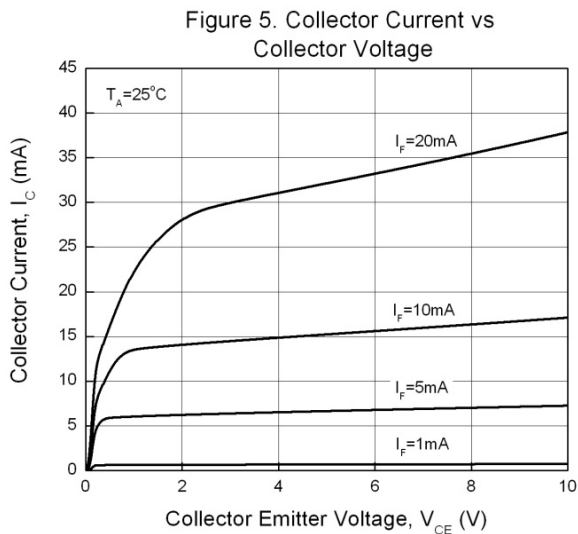
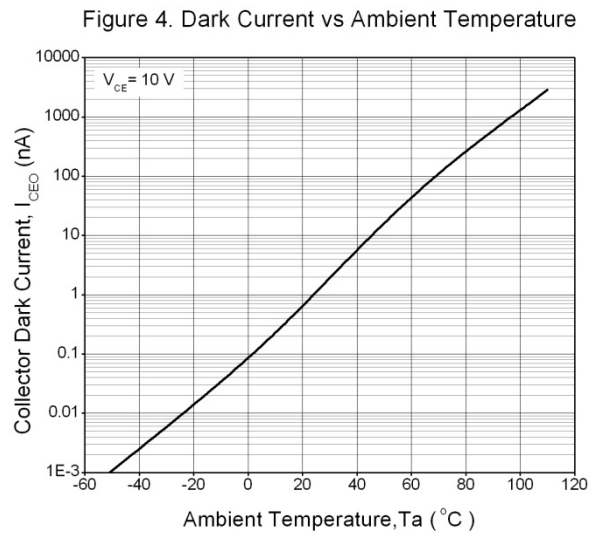
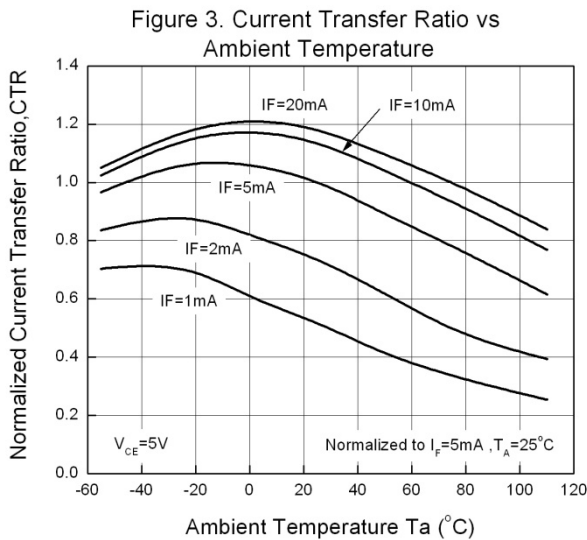
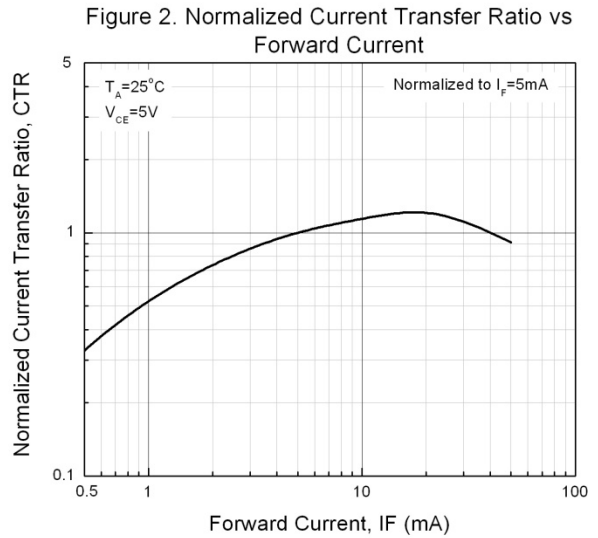
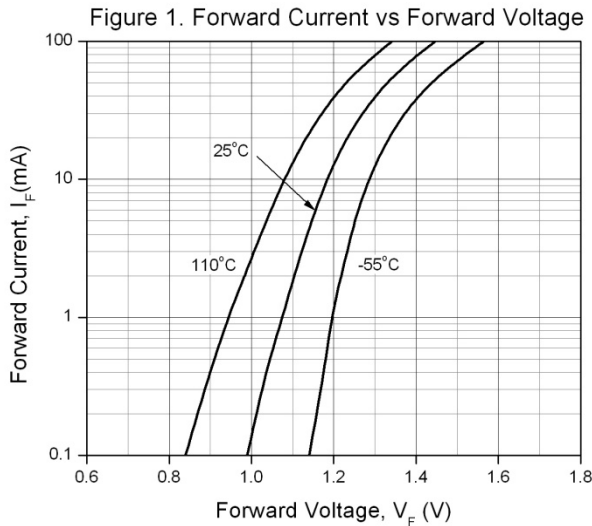
Parameter	Symbol	Min	Typ.	Max.	Unit	Condition
Collector-Emitter dark current	$I_{CEO}$	-	-	100	nA	$V_{CE} = 20\text{V}, I_F = 0\text{mA}$
Collector-Emitter breakdown voltage	$BV_{CEO}$	80	-	-	V	$I_C = 0.1\text{mA}$
Emitter-Collector breakdown voltage	$BV_{ECO}$	6	-	-	V	$I_E = 0.1\text{mA}$

**Transfer Characteristics**

Parameter	Symbol	Min	Typ.	Max.	Unit	Condition
Current Transfer ratio	EL814	20	-	300	%	$I_F = \pm 1\text{mA}, V_{CE} = 5\text{V}$
	EL814A	50	-	150		
CTR Symmetry		0.7		1.3		$I_F = \pm 1\text{mA}, V_{CE} = 5\text{V}$
Collector-emitter saturation voltage	$V_{CE(sat)}$	-	0.05	0.2	V	$I_F = \pm 20\text{mA}, I_C = 1\text{mA}$
Isolation resistance	$R_{IO}$	$5 \times 10^{10}$	$10^{11}$	-	$\Omega$	$V_{IO} = 500\text{Vdc}, 40\sim 60\%R.H$
Cut-off frequency	$f_c$	-	80	-	kHz	$V_{CE} = 5\text{V}, I_C = 2\text{mA}, R_L = 100\Omega, -3\text{dB}$
Floating capacitance	$C_{IO}$	-	0.6	1.0	pF	$V_{IO} = 0, f = 1\text{MHz}$
Rise time	$T_r$	-	7	18	$\mu\text{s}$	$V_{CE} = 2\text{V}, I_C = 2\text{mA}, R_L = 100\Omega$
Fall time	$T_f$	-	11	18	$\mu\text{s}$	

\* Typical values at  $T_a = 25^\circ\text{C}$

Typical Electro-Optical Characteristics Curves



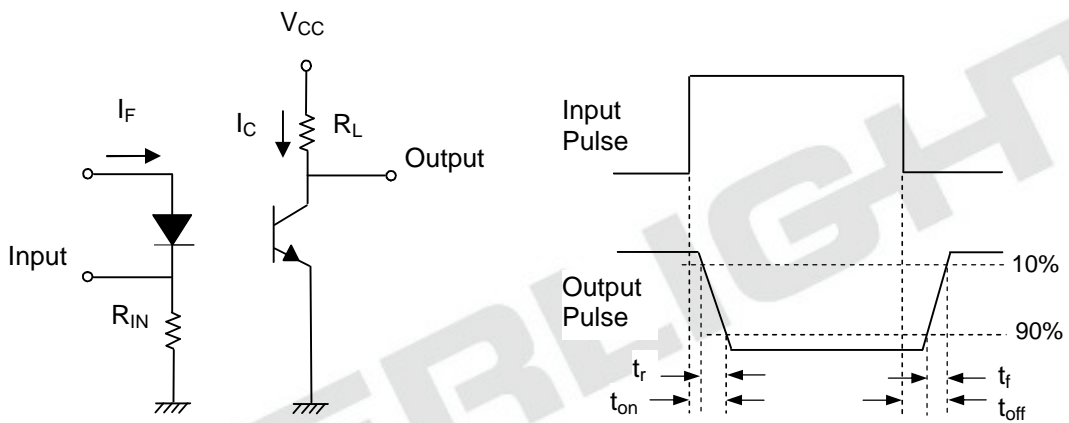
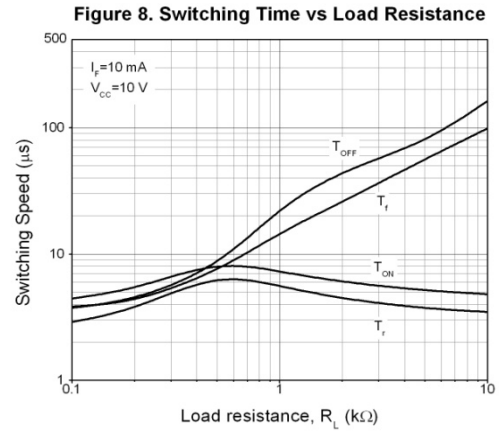
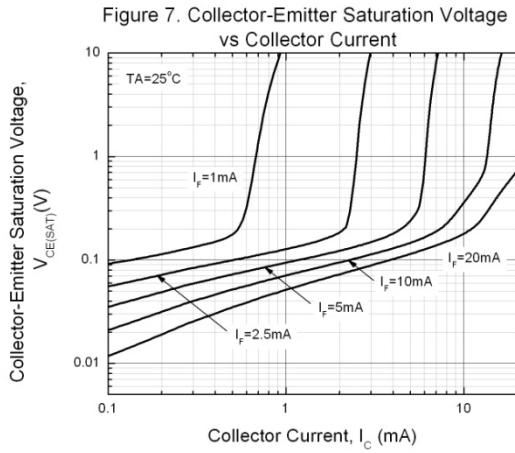


Figure 9. Switching Time Test Circuit & Waveforms

## Order Information

### Part Number

**EL814X(Y)(Z)-V**

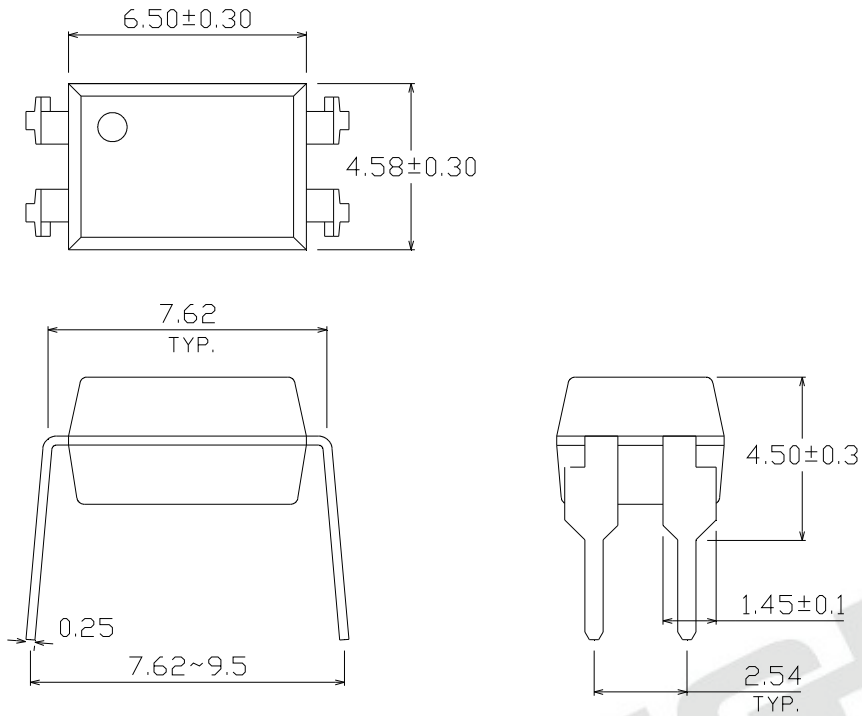
### Note

- X = Lead form option (S, S1, M or none)  
Y = CTR Rank (A or none)  
Z = Tape and reel option (TA, TB, TU, TD or none).  
V = VDE safety (optional).

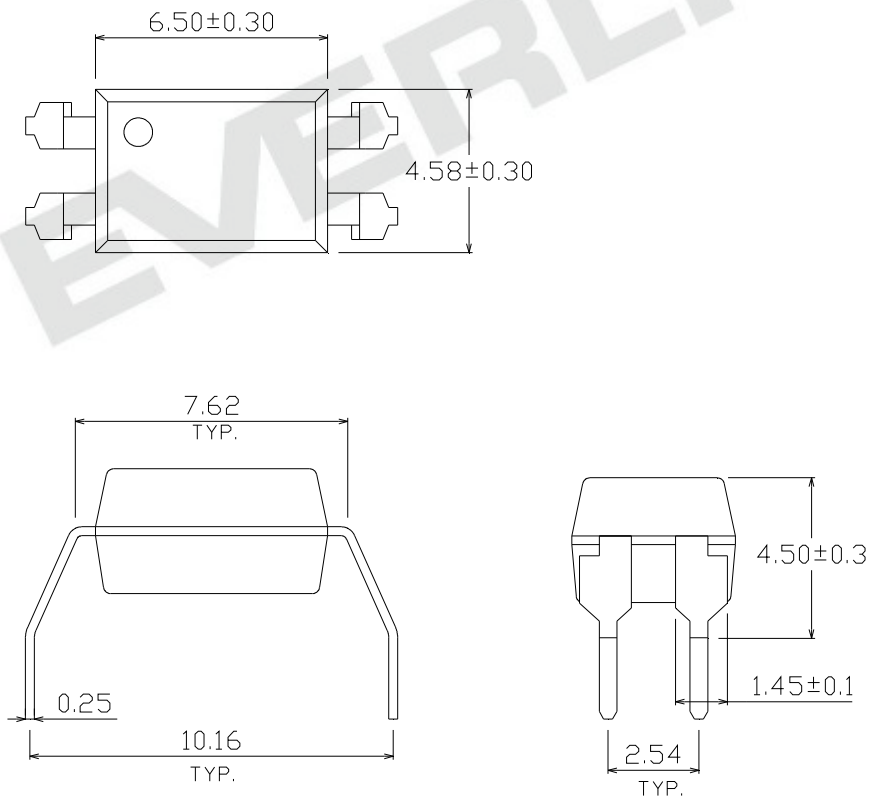
Option	Description	Packing quantity
None	Standard DIP-4	100 units per tube
M	Wide lead bend (0.4 inch spacing)	100 units per tube
S (TA)	Surface mount lead form + TA tape & reel option	1000 units per reel
S (TB)	Surface mount lead form + TB tape & reel option	1000 units per reel
S1 (TA)	Surface mount lead form (low profile) + TA tape & reel option	1000 units per reel
S1 (TB)	Surface mount lead form (low profile) + TB tape & reel option	1000 units per reel
S (TU)	Surface mount lead form + TU tape & reel option	1500 units per reel
S (TD)	Surface mount lead form + TD tape & reel option	1500 units per reel
S1 (TU)	Surface mount lead form (low profile) + TU tape & reel option	1500 units per reel
S1 (TD)	Surface mount lead form (low profile) + TD tape & reel option	1500 units per reel

Package Dimension (Dimensions in mm)

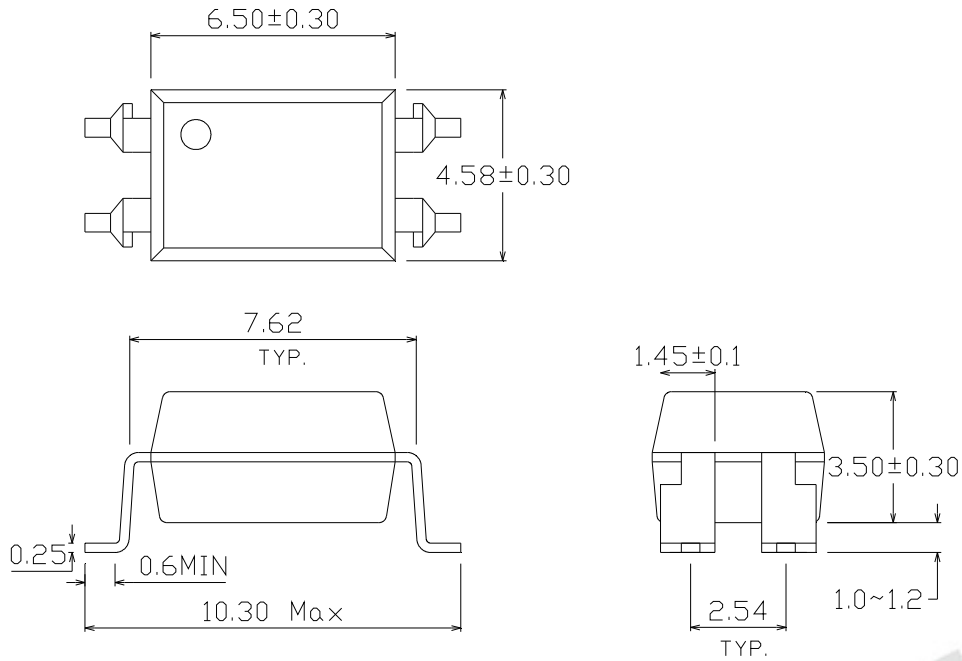
Standard DIP Type



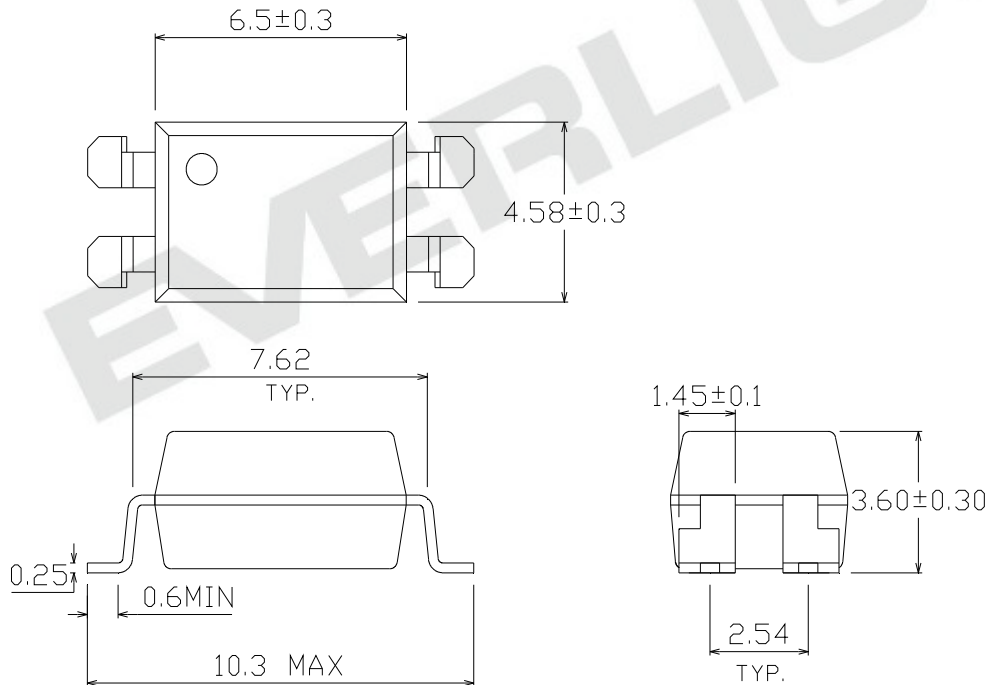
Option M Type



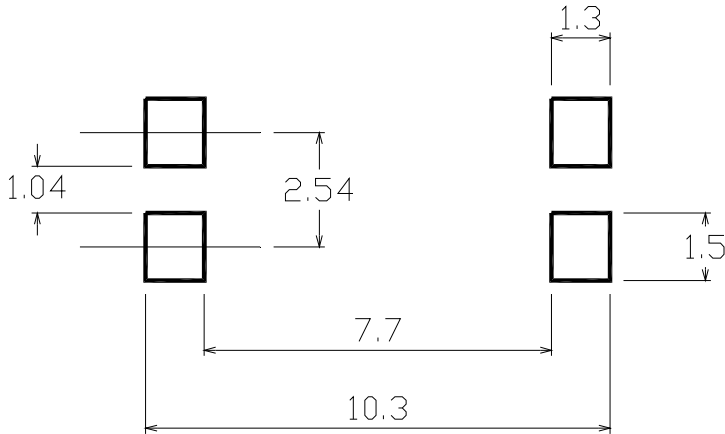
Option S Type



Option S1 Type



### Recommended pad layout for surface mount leadform



### Device Marking

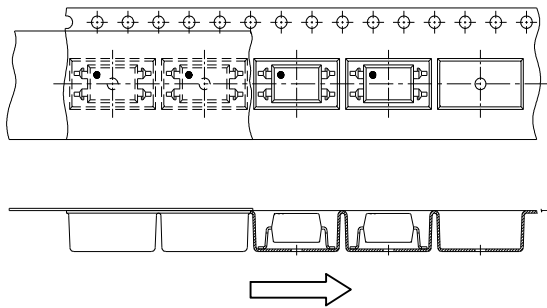


### Notes

- EL denotes EVERLIGHT
- 814 denotes Device Number
- R denotes CTR Rank (A or none)
- Y denotes 1 digit Year code
- WW denotes 2 digit Week code
- V denotes VDE (optional)

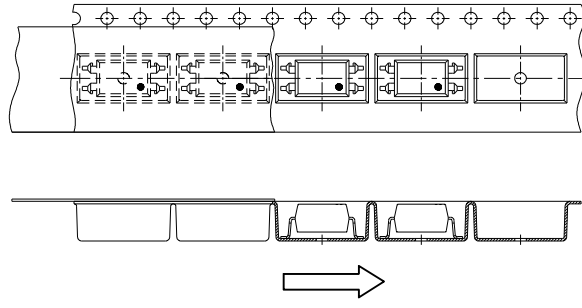
**Tape & Reel Packing Specifications**

**Option TA**



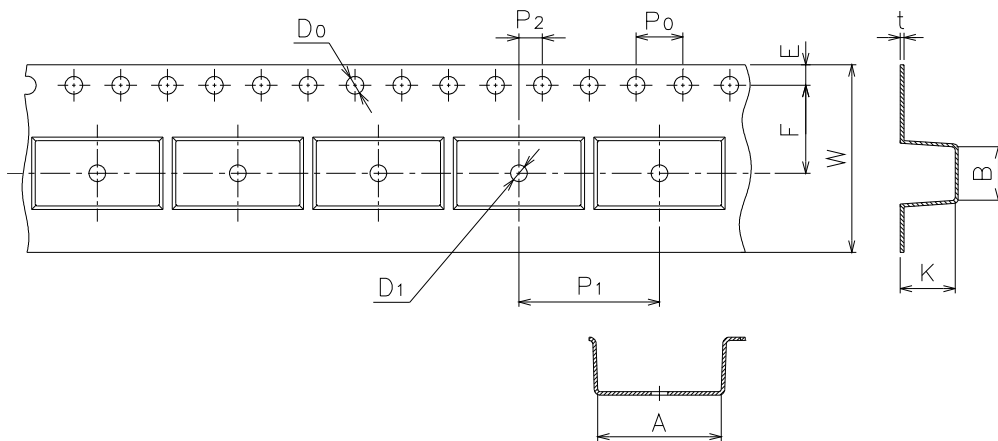
Direction of feed from reel

**Option TB**



Direction of feed from reel

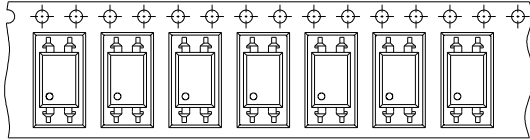
**Tape dimensions**



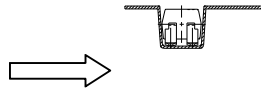
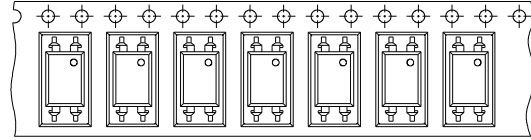
Dimension No.	<b>A</b>	<b>B</b>	<b>Do</b>	<b>D1</b>	<b>E</b>	<b>F</b>
Dimension (mm) S	10.5±0.1	4.65±0.1	1.55±0.1	1.50±0.1	1.75±0.1	7.5±0.1
Dimension (mm) S1	10.5±0.1	4.65±0.1	1.55±0.1	1.50±0.1	1.75±0.1	7.5±0.1
Dimension No.	<b>Po</b>	<b>P1</b>	<b>P2</b>	<b>t</b>	<b>W</b>	<b>K</b>
Dimension (mm) S	4.0±0.1	12.0±0.1	2.0±0.1	0.4±0.1	16.0±0.3	5.05±0.1
Dimension (mm) S1	4.0±0.1	12.0±0.1	2.0±0.1	0.4±0.1	16.0±0.3	4.75±0.1

**Tape & Reel Packing Specifications**

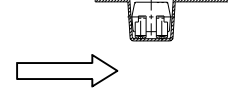
**Option TD**



**Option TU**

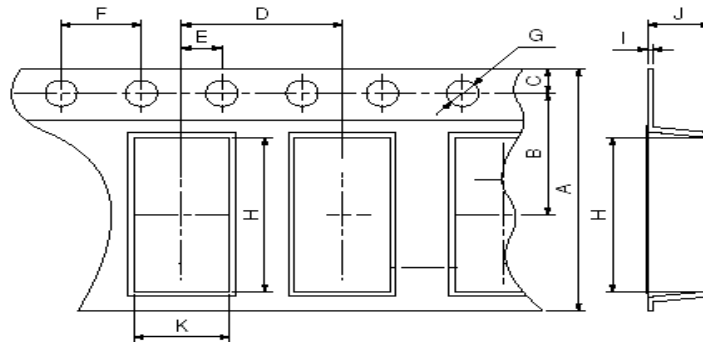


Direction of feed from reel



Direction of feed from reel

**Tape dimensions**

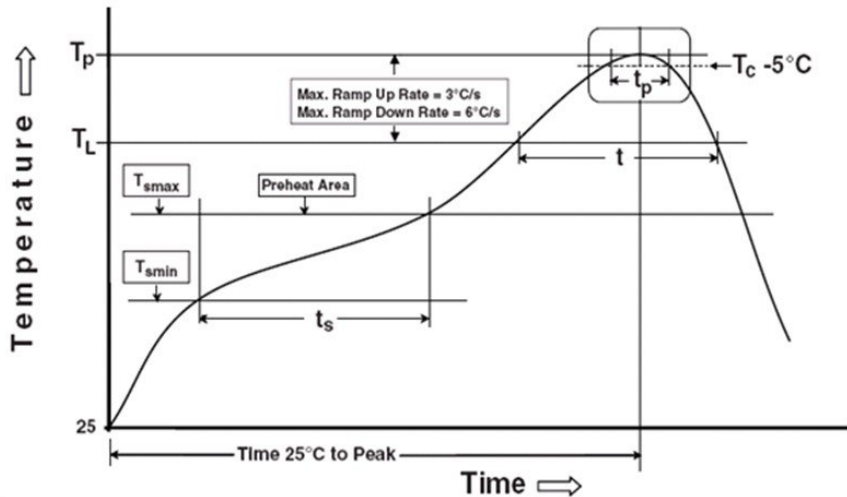


Dimension No.	<b>A</b>	<b>B</b>	<b>C</b>	<b>D</b>	<b>E</b>	<b>F</b>
Dimension(mm)	16.00±0.3	7.5±0.1	1.75±0.1	8.0±0.1	2.0±0.1	4.0±0.1
Dimension No.	<b>G</b>	<b>H</b>	<b>I</b>	<b>J</b>	<b>K</b>	
Dimension(mm)	1.5±0.1	10.4±0.1	0.4±0.1	4.60±0.1	5.1±0.1	

## Precautions for Use

### 1. Soldering Condition

#### 1.1 (A) Maximum Body Case Temperature Profile for evaluation of Reflow Profile



Note:

Reference: IPC/JEDEC J-STD-020D

#### Preheat

Temperature min ( $T_{smin}$ )	150 °C
Temperature max ( $T_{smax}$ )	200°C
Time ( $T_{smin}$ to $T_{smax}$ ) ( $t_s$ )	60-120 seconds
Average ramp-up rate ( $T_{smax}$ to $T_p$ )	3 °C/second max

#### Other

Liquidus Temperature ( $T_L$ )	217 °C
Time above Liquidus Temperature ( $t_L$ )	60-100 sec
Peak Temperature ( $T_p$ )	260°C
Time within 5 °C of Actual Peak Temperature: $T_p - 5^\circ\text{C}$	30 s
Ramp- Down Rate from Peak Temperature	6°C /second max.
Time 25°C to peak temperature	8 minutes max.
Reflow times	3 times

## DISCLAIMER

1. Above specification may be changed without notice. EVERLIGHT will reserve authority on material change for above specification.
2. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
3. These specification sheets include materials protected under copyright of EVERLIGHT corporation. Please don't reproduce or cause anyone to reproduce them without EVERLIGHT's consent.

EVERLIGHT

## Looking for pricing, stock, or lifecycle information?

Click below to explore more details on WIN SOURCE:

- [View EL814M on WIN SOURCE](#)
- [Everlight Electronics Co Ltd Information](#)

## Optimize Your Supply Chain with WIN SOURCE Solutions

- ✓ Global Sourcing Solution
- ✓ Obsolete Management
- ✓ Cost Control Management
- ✓ Shortage Management
- ✓ Alternative Solution
- ✓ Excess Inventory Management